



# TECHNICAL DATA SHEET

## SP-629 Lead Free SOLDER STICKS

### PRODUCT DESCRIPTION

PAI SP-629 RoHS Compliance Solder Sticks are being formulated with High Virgin Raw Metals Processed in state-of-the-art Vaccualloy Technology that brings world class Quality along. Here, Oxygen interaction with Alloy is Nil and thus, Dross formulation is reduced at PCB Assembly Process. Also an increase flow rate & reduced impurities found. PAI SP-629 Alloy is compatible for a typical range of Flux Application Formulas used in Electronics Industry Today.

### STORAGE AND HANDLING

- Do not use Fire near storage area.
- Store in Dry, Cool and Non-Corrosive environment.
- Wear Personal Protective Equipments while Handling.
- Wear Personal Protective Equipments while Processing.

### ALLOY COMPOSITION

| Sn  | Ag   | Cu   | Ni    | Ge    | Bi    | Zn     | Al     | Sb    | Fe    | As    | Cd     | Pb    |
|-----|------|------|-------|-------|-------|--------|--------|-------|-------|-------|--------|-------|
| Rem | 0.2% | 0.6% | 0.04% | 0.005 | 0.10% | 0.001% | 0.001% | 0.05% | 0.02% | 0.03% | 0.002% | 0.05% |
|     | -    | -    | -     | -     |       |        |        |       |       |       |        |       |
|     | 0.4% | 0.8% | 0.08% | 0.02% | Max   | Max    | Max    | Max   | Max   | Max   | Max    | Max   |

### PHYSICAL CHARACTERISTICS OF APPLICATION

|                      |  |
|----------------------|--|
| Alloy                | SnAg0.3Cu0.7                               |
| Shape                | Rectangular Form                           |
| Density              | 7.4gm/cm <sup>3</sup> at 20 <sup>0</sup> C |
| Melting Temperature  | 217 <sup>0</sup> C ~226 <sup>0</sup> C.    |
| Package Form         | 25Kgs                                      |
| Application          | Wave Soldering / HASL Process              |
| Standards Considered | JIS-Z-3282                                 |
| Shelf Life           | 10 Years                                   |



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**TECHNICAL SPECIFICATIONS**

| <b>Technical Factors Recommended</b> | <b>Specifications</b>  |
|--------------------------------------|--|
| Solder Pot Temperature               | 260°C to 272°C   |
| Dwell Time                           | 3 Sec to 5 Sec   |
| Immersion                            | 0.5% to 0.70% of PWBs Thickness that being Processed             |
| Dross Recovery                       | Once in Every 8 Hours  |
| Impurities Level Check               | In-House Specifications  |
| Cu Content                           | <1%  |
| Other Factors                        | Refer Liquid Flux Manufacturer Specifications for desired Yields |

**Note:** The recommendations stated above have been contributed for desired Solder Joints and shall modify if required based on the end user Specifications.

For more details, please visit Our Website at [www.persangalloy.com](http://www.persangalloy.com) or write to us.



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